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TDA51S-41HC SOIC package integrated isolated DC-DC converter

Features

- Ultra-small, ultra-thin, chip scale SOIC package
- Baud rate up to 150Mbps
- Wide input supply range: 3 V to 5.5 V
- High isolation to 5000Vrms
- Nanosecond propagation delay
- Integrated overload, short-circuit protection and thermal shutdown
- High CMTI: 150 kV/µs (typical)
- Industrial operating ambient temperature range: -40 $^\circ\!\mathrm{C}$ to +125 $^\circ\!\mathrm{C}$
- RoHS-Compliant Packages: SOIC16-WB

Applications

- 3.3V/5V conversion
- Bus isolated communication
- Isolated sensor interface
- Industrial automation systems
- Motor control
- Medical isolated
- Test and measurement
- Isolated ADC, DAC

Functional Description

TDA51S-41HC is a family of high-performance reinforced digital isolators with an integrated isolated DC-DC converter. TDA51S-41HC eliminate the need for a separate, isolated power supply, which results in a small form factor, total isolation solution.

TDA51S-41HC device has three forward and one reverse-direction channels, and it has fail-safe mode option. If the input signal is lost, default output is low for devices with H. In addition, other channel communication types, such as two forward channels and two reverse channels, four forward channels, four reverse channels, and many other channel combination types are under development.



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Package

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Pin Connection

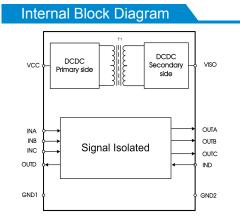
VCC 1 GND1 2 INA 3 INB 4 INC 5 OUTD 6 NC 7 GND1 8	● TDA51S-41HC	16 VISO 15 GND2 14 OUTA 13 OUTB 12 OUTC 11 IND 10 SEL 9 GND2
l]

Note: All GND1 pins are internally connected; All GND2 pins are internally connected.

Function Table

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SEL Input	Vcc	V _{ISO}
Shorted to VISO	5V	5V
Shorted to GND2 or floating	5V	3.3V
Shorted to GND2 or floating	3.3V	3.3V

Note:

1. V_{CC} = 3.3 V, SEL shorted to VISO (V_{ISO} = 5 V) is not recommended mode of configuration.

2. The SEL pin has a weak pulldown internally. For VISO = 3.3 V, the SEL pin should be strongly connected to the GND2 pin in noisy system scenarios.

Table 2. Operation Mode Table

Vcc	Input	Output	Operation
	Н	Н	Normal operation mode:
PU	L	L	A channel's output follows the input state
	OPEN	Default	Default output fail-safe mode: If a channel's input is left open, its output goes to the default high level.
PD	Х	Undetermined	

Note:

1. PU = Powered up (V_{CC} \geq 2.7 V); PD = Powered down (V_{CC} \leq 2.1 V); X = Irrelevant; H = High level; L = Low level.

2. The outputs are in undetermined state when V_{CC} < 2.1V.



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Pin Number	Pin Name	Pin Functions
1	V _{cc}	Power supply(Side 1) By using 0.1uF and 22uF ceramic capacitance GND1
2	GND1	Ground(Side 1)
3	INA	Digital input(Side 1)
4	INB	Digital input(Side 1)
5	INC	Digital input(Side 1)
6	OUTD	Digital output(Side 1)
7	NC	No Connect.
8	GND1	Ground(side 1)
9	GND ₂	Ground(Side 2)
10	SEL	VISO selection pin
11	IND	Digital input(Side 2)
12	OUTC	Digital output(Side 2)
13	OUTB	Digital output(Side 2)
14	OUITA	Digital output(Side 2)
15	GND ₂	Ground(Side 2)
16	V _{ISO}	Isolated output supply voltage determined by SEL pin. By using 0.1uF and 47uF ceramic capacitance Ground2.

Note: VISO selection pin. V_{ISO} = 5 V when SEL is connected to VISO. V_{ISO} = 3.3 V, when SEL is connected to GND2 or left floating.

Absolute Maximum Ratings

General test conditions: Free-air, normal operating temperature range (unless otherwise specified).

PARAMETERS	UNIT
Supply voltage V _{CC}	-0.5V to +6V
Input voltage V _{in}	-0.5V to Vcc+0.5V
Output current Io	-20mA to +20mA
Receiver Output current TJ	< 150°C
Operating temperature range	-40°C to +125°C
Storage temperature range	-65°C to +150°C

Important: Exposure to absolute maximum rated conditions for an extended period may severely affect the device reliability, and stress levels exceeding the "Absolute Maximum Ratings" may result in permanent damage.

Recommended Operating Conditions

	PARAMET	ERS	Min.	Nom.	Max.	Unit
Vcc	Su	oply Voltage	3		5.5	V
Vih	High-lev	vel Input Voltage	2			V
VIL	Low-lev	el Input Voltage			0.8	V
1	Liter level Outer t Orment	V _{cco} =5V	-4			
Іон	High-level Output Current	V _{CCO} =3.3V	-2			mA
		V _{cco} =5V			4	
IOL	Low-level Output Current	V _{CCO} =3.3V				mA
TA	Ambie	nt Temperature	-40		125	°C
P _D	Maximum Power Dissipation	Vcc= 5.5V, V _{ISO} = 5.5V, I _{LOAD} =130mA, all digital channels input :f=100MHz ; Duty=50%			1	w
DR	[Data Rate	0		150	Mbps

Note: V_{CCI} = signal input side supply; V_{CCO} = signal output side supply.



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5 V Input, 5 V output : Vcc= 5 V \pm 10%, T_A= -40 to 125°C, SEL shorted to Viso

	PARAMETERS	CONDITIONS	Min.	Nom.	Max.	Unit
M		External I _{ISO} =0 to 50mA	4.75	5.07	5.43	v
V _{ISO}	Isolated supply voltage	External I _{ISO} =0 to 130mA	4.5	5.07	5.43	V
VISO(LINE)	DC line regulation	$I_{\rm ISO}{=}50mA$, $V_{\rm CC}{=}4.5V$ to $5.5V$		2		
VISO(LOAD)	DC load regulation	I _{ISO} =0 to 130mA		1%		
EFF	Efficiency at maximum load current	I _{ISO} =130mA,C _L =0.1uF 10uF; V _I =0V		53%		
VCC(UVLO+)	V _{CC} under voltage threshold when supply voltage is rising			2.7		V
VCC(UVLO-)	V _{CC} under voltage threshold when supply voltage is falling		2.1			V
VHYS(UVLO)	$V_{\mbox{\scriptsize CC}}$ under voltage threshold hysteresis			0.2		V
Ін	High-level input leakage current	VIH=VCCI at INx			20	uA
lı.	Low-level input leakage current	Vi∟ = 0V at INx	-20			uA
Vон	High-level output voltage	Іон = –4 mA, Figure 8	V _{cco} – 0.4	V _{cco} – 0.2		V
Vol	Low-level output voltage	lo∟ = 4 mA, Figure 8		0.2	0.4	V
CMTI	Common-mode transient immunity	V _I = 0 V or VCC, Figure 9	100	150		kV/us
I _{SCC_SC}	DC current from supply under short circuit on V _{ISO}	V _{ISO} shorted to GND2		42		mA
V _{ISO(RIP)}	Output ripple on isolated supply (pk-pk)			60		mV

5 V Input, 3.3 V output : Vcc= 5 V \pm 10%, T_A = -40 to 125°C, SEL shorted to GND2

	PARAMETERS	CONDITIONS	Min.	Nom.	Max.	Unit
N/		External I _{ISO} =0 to 50mA	3.13	3.34	3.56	N
Viso	Isolated supply voltage	External I _{ISO} =0 to 130mA	3	3.34	3.56	V
VISO(LINE)	DC line regulation	$I_{\rm ISO}\text{=}50\text{mA}$, $V_{\rm CC}\text{=}4.5\text{V}$ to 5.5V		2		
VISO(LOAD)	DC load regulation	I _{ISO} =0 to 130mA		1%		
EFF	Efficiency at maximum load current	I _{ISO} =130mA,C _L =0.1uF 10uF; Vi=0V		48%		
VCC(UVLO+)	V _{CC} under voltage threshold when supply voltage is rising			2.7		V
VCC(UVLO-)	V _{CC} under voltage threshold when supply voltage is falling		2.1			V
VHYS(UVLO)	$V_{\mbox{\scriptsize CC}}$ under voltage threshold hysteresis			0.2		V
Ін	High-level input leakage current	Vi∺=VCCI at INx			20	uA
lıL	Low-level input leakage current	V _{IL} = 0V at INx	-20			uA
Vон	High-level output voltage	Іон = –4 mA, Figure 8	V _{CCO} – 0.4	V _{CCO} – 0.2		V
Vol	Low-level output voltage	lo∟ = 4 mA, Figure 8		0.2	0.4	V
CMTI	Common-mode transient immunity	$V_1 = 0 V \text{ or VCC}$, Figure 9	100	150		kV/us
lscc_sc	DC current from supply under short circuit on V _{ISO}	V _{ISO} shorted to GND2		38		mA
VISO(RIP)	Output ripple on isolated supply (pk-pk)			58		mV

3.3 V Input, 3.3 V output : Vcc= 3.3V \pm 10%, T_A= -40 to 125°C, SEL shorted to GND2

	PARAMETERS	CONDITIONS	Min.	Nom.	Max.	Unit
M		External I _{Iso} =0 to 50mA	3.13	3.34	3.56	v
V _{ISO}	Isolated supply voltage	External I _{ISO} =0 to 75mA	3	3.34	3.56	v
VISO(LINE)	DC line regulation	$I_{\rm ISO}{=}50mA$, $V_{\rm CC}{=}4.5V$ to $5.5V$		2		
VISO(LOAD)	DC load regulation	I _{ISO} =0 to 130mA		1%		
EFF	Efficiency at maximum load current	I _{ISO} =130mA , C∟=0.1uF 10uF; V _I =0V		47%		
VCC(UVLO+)	V _{CC} under voltage threshold when supply voltage is rising				2.7	V

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	PARAMETERS	CONDITIONS	Min.	Nom.	Max.	Unit
VCC(UVLO-)	V _{cc} under voltage threshold when supply voltage is falling		2.1			V
VHYS(UVLO)	Vcc under voltage threshold hysteresis			0.2		V
Ін	High-level input leakage current	VIH=VCCI at INx			20	uA
lı∟	Low-level input leakage current	VIL = 0V at INx	-20			uA
Vон	High-level output voltage	Іон = –4 mA, Figure 8	V _{CCO} – 0.4	V _{cco} – 0.2		V
Vol	Low-level output voltage	lo∟ = 4 mA, Figure 8		0.2	0.4	V
CMTI	Common-mode transient immunity	$V_1 = 0 V \text{ or VCC}$, Figure 9	100	150		kV/us
I _{scc_sc}	DC current from supply under short circuit on V _{ISO}	V_{ISO} shorted to GND2		32		mA
VISO(RIP)	Output ripple on isolated supply (pk-pk)			55		mV

Note: V_{CCI} = signal input side supply; V_{CCO} = signal output side supply.

Supply Current Characteristics

5 V Input, 5 V output : Vcc= 5 V \pm 10%, T_A = -40 to 125°C, SEL shorted to Viso

	PARAMETERS	CONDITIONS	Min.	Nom.	Max.	Unit
		No external I _{LOAD} ; V _I =0V		23		
		No external ILOAD ; VI=VCCI		17		
Icc	Current drawn from	All channels switching : f=1Mbps, Duty=50%; CL=15pF, No external ILOAD		20		mA
	supply	All channels switching : f=10Mbps, Duty=50%; CL=15pF, No external ILOAD		24		
		All channels switching : f=100Mbps, Duty=50%; CL=15pF, No external ILOAD		54		
	Current available to isolated supply	No external I_{LOAD} ; $V_I=0V$			128	
		No external I _{LOAD} ; V _I =V _{CCI}			130	
IISO(OUT)		All channels switching : f=1Mbps, Duty=50%; CL=15pF, No external ILOAD			128	mA
		All channels switching : f=10Mbps, Duty=50%; CL=15pF, No external ILOAD			127	
		All channels switching : f=100Mbps, Duty=50%; CL=15pF, No external ILOAD			112	

5 V Input, 3.3 V output : Vcc= 5V \pm 10%, T_A = -40 to 125°C, SEL shorted to GND2

	PARAMETERS	CONDITIONS	Min.	Nom.	Max.	Unit
Icc		No external I _{LOAD} ; V _I =0V		23		
		No external I _{LOAD} ; V _I =V _{CCI}		14		
	Current drawn from	All channels switching : f=1Mbps, Duty=50%; CL=15pF, No external ILOAD		17		mA
	supply	All channels switching : f=10Mbps, Duty=50%; CL=15pF, No external ILOAD		20		
		All channels switching : f=100Mbps, Duty=50%; CL=15pF, No external ILOAD		40		
		No external ILOAD ; VI=0V			128	
Iiso(out)		No external I _{LOAD} ; V _I =V _{CCI}			130	
	Current available to isolated supply	All channels switching : f=1Mbps, Duty=50%; C _L =15pF, No external I _{LOAD}			129	mA
		All channels switching : f=10Mbps, Duty=50%; CL=15pF, No external ILOAD			128	
		All channels switching : f=100Mbps, Duty=50%; C _L =15pF, No external I _{LOAD}			118	

3.3 V Input, 3.3 V output : Vcc= 3.3V \pm 10%, T_A = -40 to 125°C, SEL shorted to GND2

	PARAMETERS	CONDITIONS	Min.	Nom.	Max.	Unit
		No external I _{LOAD} ; V _I =0V		25		
	No external I _{LOAD} ; Vi=V _{CCI}			17		
lcc	Current drawn from supply	All channels switching : f=1Mbps, Duty=50%; C _L =15pF, No external I _{LOAD}		21		mA
		All channels switching : f=10Mbps, Duty=50%; CL=15pF, No external ILOAD	24			
		All channels switching : f=100Mbps,		48		

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	PARAMETERS CONDITIONS				Max.	Unit
		Duty=50%; C _L =15pF, No external I _{LOAD}				
		No external I _{LOAD} ; V _I =0V			73	
		No external ILOAD ; VI=VCCI			75	
I _{ISO(OUT)}	Current available to isolated supply	Duty=50%: C =15pE No oxtorpal have			74	mA
	All chan Duty=50% All chan	All channels switching : f=10Mbps, Duty=50%; CL=15pF, No external ILOAD			73	
		All channels switching : f=100Mbps, Duty=50%; CL=15pF, No external ILOAD			61	

Note:

 $1.V_{CCI}$ = signal input side supply; V_{CCO} = signal output side supply.

2. When $T_A > 115^{\circ}$ C, Current available to isolated supply should be reduced by 2mA/°C.

Transmission Characteristics 🔰 General test conditions and V_{cc}=V_{I0}= 5V, Ta = 25 $^{\circ}$ C (unless otherwise specified).

	PARAMETERS CONDITIONS		Min.	Nom.	Max.	Unit
DR	Data Rate		0		150	Mbps
PW _{minL}	Minimum Pulse Width				5.0	ns
t _{PLH} , t _{PHL}	Propagation Delay Time		6.0	10.0	15.0	ns
PWD	Pulse Width Distortion tPLH - tPHL	Figure 8		0.2	4.5	ns
t _{rk(O)}	Channel-to-channel Output Skew Time	-		0.4	2.5	ns
t _{rk(pp)}	Part-to-part Skew Time			2.0	4.5	ns
tr	Output Signal Rise Time			2.5	4.0	ns
t _f	Output Signal Fall Time	Figure 8		2.5	4.0	ns

Note:

 $1.t_{rk(o)}$ is the skew between outputs of a single device with all driving inputs connected and the outputs switching in the same direction while driving identical loads.

2.t_{rk(pp)} is the magnitude of the difference in propagation delay times between any terminals of different devices switching in the same direction while operating at identical supply voltages, temperature, input signals and loads.

Physical Specifications

PARAMETERS	Value	Unit
Weight	0.4(Typ.)	g

Test Circuits

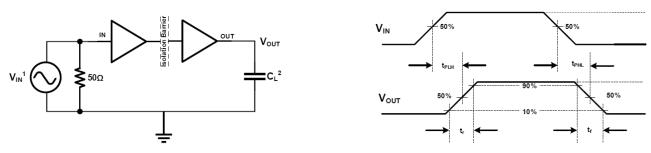


Figure 8. Timing Characteristics Test Circuit and Voltage Wave forms

Note:

1. A square wave generator generate the VIN input signal with the following constraints: waveform frequency \leq 100kHz, 50% duty cycle, t_r \leq 3ns, t_f \leq

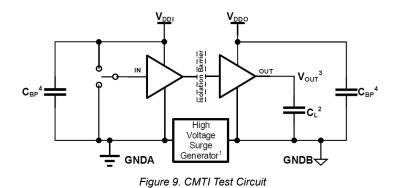
3ns. Since the waveform generator has an output impedance of $Z_{out} = 50\Omega$, the 50 Ω resistor in the figure is used for matching. There is no need in the actual application.

2. C_L is the load capacitance about 15pF together with the instrumentation capacitance. Since the load capacitance influence the output rising time, it's a key factor in the timing characteristic measurement.



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Note:

1. The High Voltage Surge Generator generates repetitive high voltage surges with > 1.5kV amplitude and <10ns rise time and fall time to reach

common-mode transient noise with > 150kV/µs slew rate.

2. C_{L} is the load capacitance about 15pF together with the instrumentation capacitance.

3. Pass-fail criteria: The output must remain stable whenever the high voltage surges come.

4. CBP is the 0.1 to 1uF bypass capacitance.

Detailed Description

TDA51S-41HC has a high-efficiency, low-emissions isolated dc-dc converter, with high-speed isolated data channels.

The dc-to-dc converter section of the TDA51S-41HC devices works on principles that are common to most modern power supplies. The devices have a split controller architecture with isolated PWM feedback. VCC power is supplied to an oscillating circuit that switches current into a high-Q on-chip air-core transformer which provide high efficiency and low radiated emissions. The integrated transformer uses thin film polymer as the insulation barrier. Power transferred to the secondary side is rectified and regulated to a value of 3.3 V or 5 V, depending on the setting of the SEL pin. The secondary (VISO) side controller regulates the output by creating a PWM control signal that is sent to the primary side by a dedicated isolated data channel. The PWM modulates the oscillator circuit to control the power being sent to the secondary side. Feedback allows for significantly higher power and efficiency and ensures low overshoots and undershoots during load transients. Undervoltage lockout (UVLO) with hysteresis is integrated on the VCC and VISO supplies which ensures robust system performance under noisy conditions. An integrated soft-start mechanism ensures controlled inrush current and avoids any overshoot on the output during power up. Short-circuit protection: TDA51S-41HC has current-limiting protection to prevent the drive circuit from short-circuiting to positive and negative supply voltages. The power dissipation increases when a short circuit occurs. The short-circuit protection function protects the driver stage from damage.

The high-speed isolated data channels use a simple ON-OFF keying (OOK) modulation scheme to transmit signal across the SiO2 isolation capacitors that provide a robust insulation between two different voltage domain and act as a high frequency signal path between the input and the output. The transmitter (TX) modulates the input signal onto the carrier frequency, that is, TX delivers high frequency signal across the isolation barrier in one input state and delivers no signal across the barrier in the other input state. Then the receiver rebuilds the input signal according to the detected in-band energy. The capacitor-based signal path is fully differential to maximize noise immunity, which is also known as common-mode transient immunity. The capacitively-coupled architecture provides much higher electromagnetic immunity compared to the inductively coupled one.

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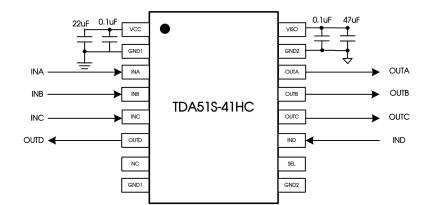


Figure 10. The typical model applies telephone

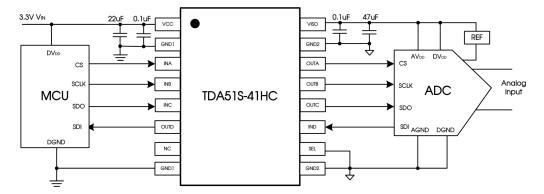


Figure 11. Isolated Power and SPI for ADC Sensing Application with TDA51S-41HC

Design requirement:

Parameter	Value
Input voltage V _{IN}	3.0V to 5.5V
Decoupling capacitors between $V_{\mbox{\scriptsize CC}}$ and GND1	0.1uF, 22uF
Decoupling capacitors between $V_{\mbox{\scriptsize ISO}}\mbox{and }GND2$	0.1uF, 47uF

Because of the higher current flowing though the VCC and VISO power supplies of TDA51S-41HC, higher decoupling capacitors usually provide better noise and ripple performance. Although a 10uF capacitor is enough to ensure the normal operation of the product, it is still strongly recommended to use a higher decoupling capacitor(such as 22uF, 47uF) on both VCC and VISO pins to the respective grounds to achieve the best performance.

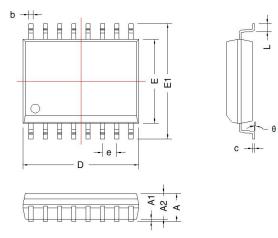
Ordering Information

Part number	Package	Number of pins	Product marking	Tape & Reel
TDA51S-41HC	SOIC	16	TDA51S-41HC	1K/REEL



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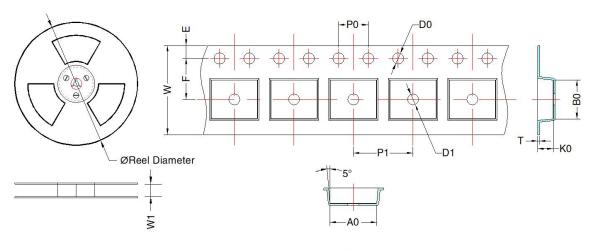


		SOIC-16				
Maula	Dimens	ion(mm)	Dimension(inch)			
Mark	Min	Max	Min	Max		
Α	2.35	2.65	0.093	0.104		
A1	0.10	0.30	0.004	0.012		
A2	2.25	2.35	0.089	0.093		
D	10.2	10.4	0.402	0.409		
E	7.4	7.6	0.291	0.299		
E1	10.1	10.5	0.340	0.413		
L	0.55	0.85	0.022	0.033		
b	0.35	0.43	0.014	0.017		
е	1.27	TYP	0.05	TYP		
С	0.15	0.30	0.006	0.012		
θ	0°	8°	0°	8°		

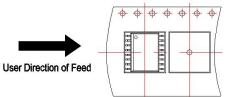
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The orientation of IC in tape



Device	Package Type	MPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	T (mm)	W (mm)	E (mm)	F (mm)	P1 (mm)	P0 (mm)	D0 (mm)	D1 (mm)
TDA51S-41HC	SOIC-16	1000	330.0	24.4	10.8 ± 0.2	10.7 ± 0.2	2.9 ± 0.2	0.3 ± 0.05	24.0 ± 0.3	1.75 ± 0.1	10.5 ± 0.1	12.0 ± 0.1	4.0 ± 0.1	1.5 ± 0.1	1.5 ± 0.1

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Address: No. 5, Kehui St. 1, Kehui Development Center, Science Ave., Guangzhou Science City,HuangpuDistrict, Guangzhou, P. R. ChinaTel: 86-20-38601850Fax: 86-20-38601272E-mail: info@mornsun.cnwww.mornsun-power.com

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